# EBT Technologies Ltd at NEPCON 96

Scottish company EBT Technologies exhibited for the first time at the NEPCON 96 show at the UK's Birmingham NEC, showing products from its wide range of lamps and LED indicators. Multi chip LED and LED indicators were a significant part of the exhibit.

In voltages ranging from 6V to 230V, the multi-chip LEDs are available in a range of colours — red, green, yellow and blue with a rated life of 100 000 hrs. The LED indicators are available with bezel finishes in either satin or black chrome and in colours of red, green, yellow and blue. Ingress protection is to IP40 to IP67 and the indicators have a voltage range of 2V to 230V. Extremely long life is a feature of the LED indicators — up to 100 000 hrs.

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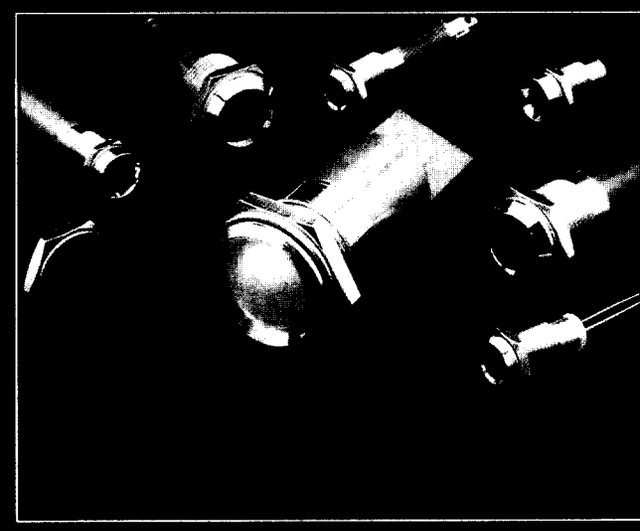

## Furukawa expands Iwaki plant

At the Iwaki plant in Fukushima Prefecture, Japan, Furukawa is expanding production of III-V materials in response to growing demand for LEDs. It recently expanded the plant at a cost of ¥1.1 bn boosting capacity for production of high-purity metals by 19%, to 5 tonnes per month, and doubled its production of GaP to 500 tonnes per month. Furukawa is also boosting production of high-purity GaAs.

## Hind gets SIDT System

SIDT Coatings Systems Inc., a subsidiary of SI Diamond (Houston, TX, USA) has sold to Hind High Vacuum Company Pvt. Ltd. (Bangalore, India) a PVD vacuum coating system, valued at $450 000 for shipment this summer.

"We believe that SIDT's coating systems unit is among the best deposition equipment available," says Dr Howard K. Schmidt, SIDT's chairman and CEO. "Design, production and delivery of state-of-the-art coating equipment represent a significant business opportunity for SIDT, and we shall pursue it aggressively during 1996."

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## Thomson, Daimler joint venture .....

Thomson-CSF is to form a joint venture with two Daimler-Benz AG subsidiaries to develop, make and sell GaAs devices.

T-CSF will own 50% of the new company while Daimler-Benz Aerospace (Dasa) and TEMIC will respectively hold 30 and 20%, capital is F50 m

Sales are expected to reach FF250 m (US$50 m) by 2000.

## SOITEC's 3rd capital OK

SOITEC, the Grenoble, France, SOI wafers company wafers has completed a third round of capital financing. This will fund both a pilot line and production line for UNIBOND® wafers. These are manufactured using a technique recently introduced by SOITEC that combines the advantages of both the bonding and SIMOX methods of making SOI wafers developed with LETI, the French technology and instrumentation lab.

The pilot line is complete and the new UNIBOND production line, which will be in a separate facility should be completed in mid-1997.

According to André Auberton-Hervé, corporate president of SOITEC, there was recently a 50% growth in the worldwide demand for SOI wafers, and a drastic increase in large-volume production is expected in 1997-98 for mainstream applications such as portable telecom systems etc. will drive the SOI market for the next few years.

"This new technology enables high-volume production of SOI wafers for the first time. It is why we expect our annual capacity to reach more than 100 000 8-inch wafers per year in 1996, with production expected to be one million wafers per year by 2000, in line with anticipated demand. The new investment, will give us a capacity 5 to 10 times greater than the competition." Because we've always been profitable and because UNIBOND is a very important technological step, the same international VC firms who've supported us before have re-invested," he added.

The well-established international VC firms that SOITEC has aligned itself with have now tripled their funding: Banque National de Paris, through its VC firms BANEXI, BANEXI VENTURE and FINOVECTRON, is the largest investor, while INNOVACOM, a VC firm owned by France Telecom, also increased capital share.

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